



Negative E-Beam Resists AR-N 7500

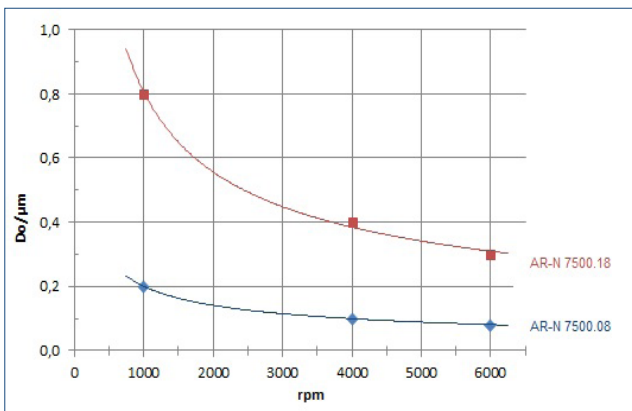
AR-N 7500 e-beam resists for mix & match

High-resolution e-beam resists for the production of integrated circuits

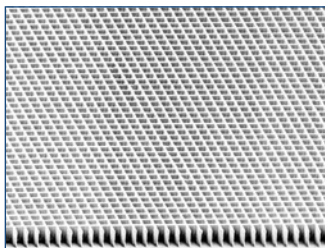
Characterisation

- e-beam, deep UV, i-line, g-line
- intermediate sensitivity
- mix & match-processes between e-beam and UV exposure 310 - 450 nm, positive or negative depending on the exposure wavelength chosen
- high resolution, process-stable (no CAR)
- plasma etching resistant, temp.-stable up to 120 °C
- novolac, naphthoquin. diazide, organic crosslink. a.
- safer solvent PGMEA

Spin curve



Structure resolution



AR-N 7500.18
Film thickness 400 nm
Lattice with 70 nm lines

Properties I

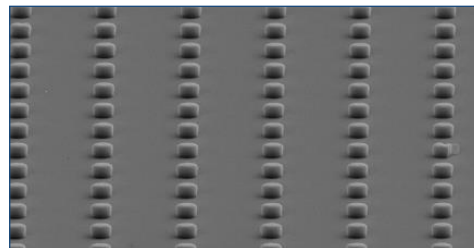
Parameter / AR-N	7500.18	7500.08
Solids content (%)	18	8
Viscosity 25 °C (mPas)	4	2
Film thickness/4000 rpm (μm)	0.4	0.1
Resolution best value (nm)	40	
Contrast	5	
Flash point (°C)	42	
Storage temperature (°C) *	10-18	

* Products have a guaranteed shelf life of 6 months from the date of sale if stored correctly and can also be used without guarantee until the date indicated on the label.

Properties II

Glass trans. temperature (°C)	108	
Dielectric constant	3.1	
Cauchy coefficients	N ₀	1.614
	N ₁	157.1
	N ₂	0
Plasma etching rates (nm/min) (5 Pa, 240-250 V Bias)	Ar-sputtering	8
	O ₂	170
	CF ₄	40
	80 CF ₄ + 16 O ₂	90

Resist structures



AR-N 7500.18,
rows of cylinders
with a diameter of
500 nm

Process parameters

Substrate	Si 4" waver
Soft bake	85 °C, 90 s, hot plate
Exposure	ZBA 21, 30 kV
Development	AR 300-47, 4 : 1, 60 s, 22 °C

Process chemicals

Adhesion promoter	AR 300-80 new
Developer	AR 300-46, 300-47
Thinner	AR 300-12
Remover	AR 300-76, AR 300-73

Negative E-Beam Resists AR-N 7500

Process conditions

This diagram shows exemplary process steps for AR-N 7500 resists. All specifications are guideline values which have to be adapted to own specific conditions. For further information on processing, ☞ "Detailed instructions for optimum processing of e-beam resists". For recommendations on waste water treatment and general safety instructions, ☞ "General product information on Allresist e-beam resists".

Coating		AR-N 7500.18 4000 rpm, 60 s, 0.4 μm
Soft bake ($\pm 1\text{ }^\circ\text{C}$)		85 $^\circ\text{C}$, 2 min hot plate or 85 $^\circ\text{C}$ 30 min convection oven
E-beam exposure		ZBA 21, 20 kV Exposure dose (E_0): 180 $\mu\text{C}/\text{cm}^2$
Development (21-23 $^\circ\text{C} \pm 0,5\text{ }^\circ\text{C}$) puddle Rinse		AR 300-47, 4 : 1 60 s DI-H ₂ O, 30 s
Post-bake (optional)		120 $^\circ\text{C}$, 1 min hot plate or 120 $^\circ\text{C}$, 25 min convection oven for enhanced plasma etch resistance
Customer-specific technologies		Generation of semiconductor properties
Removal		AR 300-76 or O ₂ plasma ashing

Developments recommendations

optimal suitable

Developer	AR 300-26	AR 300-35	AR 300-47
AR-N 7500.18 ; .08	1 : 4 ; 1 : 7	4 : 1 ; 1 : 1	4 : 1

Processing instructions

These resists are predestined for e-beam exposure, but also suitable for UV exposure. Mix & match processes are possible, if both exposure methods are carefully coordinated. During e-beam exposure, the resist works in a negative mode. If these resists are exposed to UV, they also work in a negative mode if image-wise exposure is performed at 310 to 365 nm, followed by flood exposure at $> 365\text{ nm}$ (optimum g-line). The exposure dose is in this case roughly 100 mJ/cm^2 (i-line) for a film thickness of 400 nm. With an additional tempering step (85 $^\circ\text{C}$, 2 min hot plate) after image-wise exposure, the sensitivity can be slightly increased. A positive image is obtained after image-wise UV exposure at 365 - 450 nm without subsequent flood exposure. The developer dilution should be adjusted with DI water in such a way that the development time is in a range of 30 and 120 s at 21 - 23 $^\circ\text{C}$.